

## Product/Process Change Notification

N° 2021-150-B2      **!! UPDATE !!**

- Updated information marked in **BLUE TYPE**
- Original PCN N° 2021-150-A2 dated 2022-03-18

Dear customer,

please find attached an updated PCN for your attention:

**FINAL PCN: Change of parts of wafer production from Xintec Inc., Taiwan to Vanguard International Semiconductor Corporation, Taiwan and additional assembly site for D2Pak, Dpak, TO220 Mosfets**

If you have any questions, please do not hesitate to contact your local sales office.

Infineon Technologies AG

Postal address D-81726 München    Internet [www.infineon.com](http://www.infineon.com)    Headquarters Am Campeon 1-15, D-85579 Neubiberg    Phone +49 (0)89 234-0

Chairman of the Supervisory Board Dr. Wolfgang Eder

Management Board Jochen Hanebeck (CEO), Dr. Helmut Gassel, Constanze Hufenbecher, Dr. Sven Schneider, Dr. Rutger Wijburg

Registered office Neubiberg    Commercial register Amtsgericht München HRB 126492

# Product/Process Change Notification

N° 2021-150-B2      **!! UPDATE !!**

- Updated information marked in **BLUE TYPE**
- Original PCN N° 2021-150-A2 dated 2022-03-18

## Products affected

Please refer to attached affected product list PCN\_2021-150-B2\_[customer-no].pdf

## Detailed change information

**Subject:** FINAL PCN: Change of parts of wafer production from Xintec Inc., Taiwan to Vanguard International Semiconductor Corporation, Taiwan and additional assembly site for D2Pak, Dpak, TO220 Mosfets

**Reason/Motivation:** **Due to current wafer supply on allocation and Front End Xintec site closure on December 2022 with no option to extend, Infineon views this closure as a high risk for delivery disruption if the PCN is not approved within the next 6 months. Infineon encourages our customers to perform an expedited PCN review/approval within the next 3-6 months**

Description	<u>Old</u>	<u>New</u>
<b>PROCESS - WAFER PRODUCTION:</b> New / change of metallization (specifically chip backside)	Back Grind/Back Metal: Grind A, Spin Etch	Back Grind/Back Metal: Grind B, Wet Etch Bench
<b>PROCESS - WAFER PRODUCTION:</b> Move all or parts of production to a different wafer fab site	Xintec Inc., Taoyuan City, Taiwan	Vanguard International Semiconductor Corporation, Hsinchu, Taiwan
<b>PROCESS - ASSEMBLY:</b> Change of lead frame finishing material / area (internal)	D2pak, Dpak, TO220 only: Ni plated in all area Cu on die pad	D2pak, Dpak, TO220 only and TFME: Only Bare Cu in all area except T-post with Ni plate
<b>PROCESS - ASSEMBLY:</b> Change of mold compound / encapsulation material	TO220 only: MG15F-35A	TO220 only: KE-G300BH
<b>PROCESS - ASSEMBLY:</b> Change of product marking	D2pak, Dpak, TO220 only: No Site code	D2pak, Dpak, TO220 only: TFME affected only: Site Code M
<b>PROCESS - ASSEMBLY:</b> Move all or parts of production to a different assembly site	D2pak, Dpak, TO220 only: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico	D2pak, Dpak, TO220 only: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico and Tongfu Microelectronics Co., Ltd (TFME)

# Product/Process Change Notification

**N° 2021-150-B2      !! UPDATE !!**

- Updated information marked in **BLUE TYPE**
- Original PCN N° 2021-150-A2 dated 2022-03-18

<b>TEST FLOW:</b>	D2pak, Dpak, TO220 only: Final Test	D2pak, Dpak, TO220 only: Final Test ,
<b>Move of all or part of electrical wafer test and/or final test to a different test site</b>	Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico	Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico and Tongfu Microelectronics Co., Ltd (TFME)

## Product identification

Traceability is ensured via lot code

## Anticipated impact of change

Based on the qualification performed, Infineon does not expect any impact on quality, function and reliability.  
Please refer to QTR

DeQuMa-ID(s): SEM-PW-06 / SEM-PW-13 / SEM-PA-04 / SEM-PA-11 / SEM-PA-13 / SEM-PA-18 / SEM-TF-01

## Attachments

PCN_2021-150-B2_[customer-no].pdf	affected product list
2_cip21150_B2	qualification report

## Time schedule

	2021-150-A2	2021-150-B2
Final qualification report	2022-03-15	
First samples available	2022-03-15	
Intended start of delivery [1]	2022-09-15	
Last order date (LOD) [2]	n.a.	2022-06-30
Last delivery date (LDD) [3]	n.a.	2022-12-30

[1] Provided date or earlier after customer approval

[2] Last time buy volume to be placed latest until LOD

[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

If you have any questions, please do not hesitate to contact your local sales office.

## PCN 2021-150-B2

FINAL PCN: Change of parts of wafer production from Xintec Inc., Taiwan to Vanguard International Semiconductor Corporation, Taiwan and additional assembly site for D2Pak,Dpak,TO220 Mosfets



Affected products sold to DIGI-KEY (4002348)

Sales name	SP number	OPN	Package	Customer part number
AUIRF1324WL	SP001516588	AUIRF1324WL	PG-TO262-3-903	AUIRF1324WL
AUIRF1404Z	SP001520218	AUIRF1404Z	PG-TO220-3-904	AUIRF1404Z
AUIRF3205Z	SP001518518	AUIRF3205Z	PG-TO220-3-904	AUIRF3205Z
AUIRF540Z	SP001516500	AUIRF540Z	PG-TO220-3-904	AUIRF540Z
AUIRFP4568	SP001519624	AUIRFP4568	PG-TO247-3-901	AUIRFP4568
AUIFR3806TRL	SP001521230	AUIFR3806TRL	PG-TO252-3-901	AUIFR3806TRL
AUIFR4620TRL	SP001516660	AUIFR4620TRL	PG-TO252-3-901	AUIFR4620TRL
AUIRFS3107TRL	SP001521708	AUIRFS3107TRL	PG-TO263-3-901	AUIRFS3107TRL
AUIRFS4310ZTRL	SP001516740	AUIRFS4310ZTRL	PG-TO263-3-901	AUIRFS4310ZTRL